### QUALITY ASSURANCE

#### Standard Process for Commercial MMIC Chips (Die)

1. Per P10N02, Receiving Inspection

2. Per 101099, Wafer Incoming Inspection Procedure

3. Per 101099, Wafer Incoming Inspection Procedure

4. Per W10N03, Wafer Inspection Procedure
   - Serialization
   - Backside Metal
   - Adhesion
   - Surface Defects 50X Magnification

5. Per W10N03, Wafer Inspection Instruction
   - FET Structures 200X Magnification
   - Airbridges
   - Chipouts

   - 4 Die/Wafer Lot
   - Pull 12 Wires (0 Rejects)

   - 5 Die
   - Backside Metallized Wafer Only

8. Per Test Document/Product Data Sheet
   - Room Temperature

9. Per P03N01, Quotation, Order Entry and Contract Review
   - Customer PO

10. Per P09N02, Quotation, Order Entry and Contact Review
    - Customer PO

11. Per W15N02, Packaging
    - Black Conductive Waffle Pack
    - Cover & Tyvek Paper Insert (2)
    - Black Conductive Gel-Pak

12. Per W10N02, MMIC Visual Inspection
    - GaAs Commercial Visual (150X Minimum Magnification
      MIL-STD-883 Method 2010B is available)

13. Per P15N04, Handling, Storage, Packaging, Preservation & Delivery